

Notice of References Cited

Application/Control No.

10/593,809

Applicant(s)/Patent Under
Reexamination
NARAYAN ET AL.

Examiner

JONATHAN C. LANGMAN

Art Unit

1794

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U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
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FOREIGN PATENT DOCUMENTS

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	N					
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	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Catania et al., "Low resistivity body-centered cubic tantalum thin films as diffusion barriers between copper and silicon", J. Vac. Sci. Technol. A, Vol. 10, No. 5, 1992, pgs 3318-3321.
	V	Ino et al. "Ion energy, ion flux, and ion species effects on crystallographic and electrical properties of sputter deposited Ta thin films", J. Vac. Sci. Technol. A, Vol. 15, No. 5, 1997, pgs 2627-2635.
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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